

Irish Standard I.S. EN 16602-70-11:2015

Space product assurance - Procurement of printed circuit boards

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I.S. EN 16602-70-11:2015

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Space product assurance - Procurement of printed circuit boards

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Foreword

This document (EN 16602-70-11:2015) has been prepared by Technical Committee CEN/CLC/TC 5 "Space", the secretariat of which is held by DIN.

This standard (EN 16602-70-11:2015) originates from ECSS-Q-ST-70-11C.

This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by July 2015, and conflicting national standards shall be withdrawn at the latest by July 2015.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN [and/or CENELEC] shall not be held responsible for identifying any or all such patent rights.

This document has been prepared under a mandate given to CEN by the European Commission and the European Free Trade Association.

This document has been developed to cover specifically space systems and has therefore precedence over any EN covering the same scope but with a wider domain of applicability (e.g. : aerospace).

According to the CEN-CENELEC Internal Regulations, the national standards organizations of the following countries are bound to implement this European Standard: Austria, Belgium, Bulgaria, Croatia, Cyprus, Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.

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1 Scope

This Standard defines the requirements imposed on the customer, the supplier and the qualified PCB manufacturer for PCB procurement.

The requirements of clause 7 apply to both qualification and procurement of finished PCBs and do not include the manufacturing tolerances.

This Standard is applicable for the following type of boards:

- Rigid PCBs (single-sided, double-sided, multilayer, sequential multilayer and PCBs with metal core)
- Flexible PCBs (single-sided and double-sided)
- Rigid-flex PCBs (multilayer and sequential multilayer)
- High frequency PCBs
- Special PCBs.

PCBs are used for the mounting of components in order to produce PCB assemblies performing complex electrical functions. The PCBs are subjected to thermo-mechanical stresses during their assembly such as mounting of components by soldering, rework and repair under normal terrestrial conditions. In addition the assembled PCB is subjected to the environment imposed by launch and space flights. Therefore the qualification of a PCB supplier to ECSS-Q-ST-70-10 is of extreme importance before the procurement of PCB for space usage.

This standard may be tailored for the specific characteristics and constraints of a space project in conformance with ECSS-S-ST-00.



Product Page

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